



## Material Content Data Sheet



<b>Sales Product Name</b>		SPU03N60C3		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000851420						
<b>Package</b>		PG-TO251-3-21		<b>Weight*</b>		350.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.326	0.66	0.66	6636	6636
leadframe	non noble metal	tin	7440-31-5	0.273	0.08		780	
	non noble metal	copper	7440-50-8	181.882	51.92	52.00	519031	519811
wire	non noble metal	aluminium	7429-90-5	0.492	0.14	0.14	1403	1403
encapsulation	organic material	carbon black	1333-86-4	1.349	0.38		3848	
	inorganic material	antimonytrioxide	1309-64-4	2.820	0.80		8047	
	plastics	brominated resin	-	3.188	0.91		9096	
	plastics	epoxy resin	-	23.294	6.65		66472	
	inorganic material	silicondioxide	60676-86-0	91.949	26.24	34.98	262390	349853
leadfinish	non noble metal	tin	7440-31-5	3.976	1.13	1.13	11345	11345
plating	non noble metal	nickel	7440-02-0	0.344	0.10	0.10	982	982
solder	noble metal	silver	7440-22-4	0.059	0.02		169	
	non noble metal	tin	7440-31-5	0.047	0.01		135	
	non noble metal	lead	7439-92-1	2.259	0.64	0.67	6446	6750
heatspreader	non noble metal	iron	7439-89-6	0.036	0.01		103	
	inorganic material	phosphorus	7723-14-0	0.011	0.00		31	
	non noble metal	copper	7440-50-8	36.124	10.31	10.32	103086	103220
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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